

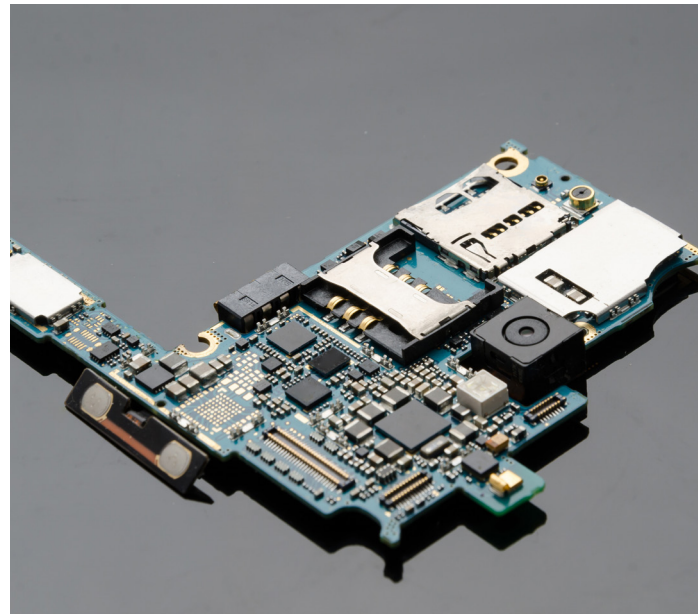
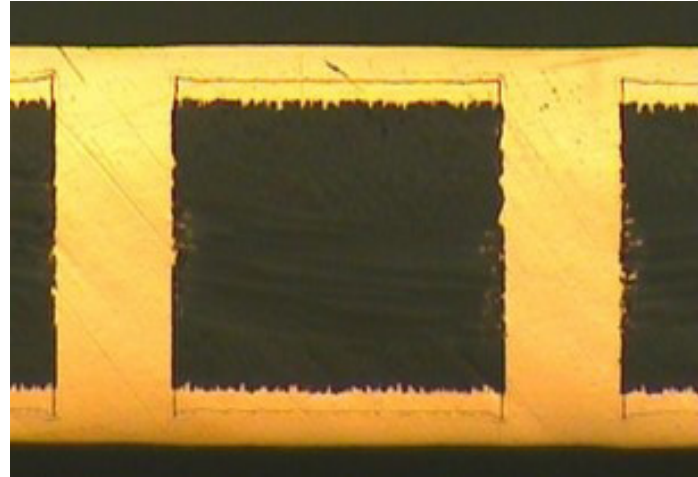
Systek™ THF Series

Copper Through Hole Filling Metallization

Better Through Holes with Reduced Plating Times

The Systek™ THF Series is the first through hole filling process that eliminates voiding, reduces cycle time, and provides solid copper through hole structures. Whether design goals include improved thermal performance, better structural integrity, or space saving design enhancements, the Systek THF Series is the through hole filling solution that delivers solid copper filled through holes at high plating speeds with minimal waste.

The advanced technology of the Systek THF Series controls surface copper buildup and fills through holes in a wide range of board thicknesses and hole diameters in a fraction of the time with less wasted metal than DC processes can deliver. This pure, void-free copper is sure to enhance the structural performance and reliability of a wide range of advanced PCB designs.



KEY FEATURES

- Unparalleled cavity free filling of through holes vs DC copper
- Flat filling for subsequent stack build ups
- Minimization of surface copper for HDI applications
- Improved thermal conductivity for heat management applications
- Capable of filling laser and mechanically drilled through vias
- Drastically reduced plating times
- Elimination of conductive plug and planarization processes
- Provides enhanced design freedom



MacDermid Enthone

CIRCUITRY SOLUTIONS

Systek™ THF Series

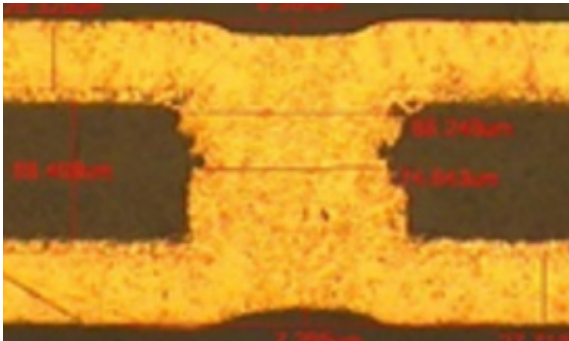
Copper Through Hole Filling Metallization

Thermal Management and Design Freedom.

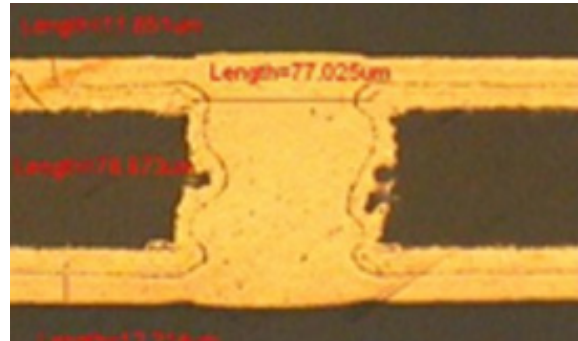
The Systek™ THF Series reduces manufacturing process steps while allowing IC substrate fabricators improvements in package reliability, thermal design efficiency and circuit density. With its void free deposit and flat surface profile after plating, the Systek THF Series is an excellent solution for advanced HDI designs.

Faster than DC Plating with Less Waste

Direct Current Plating

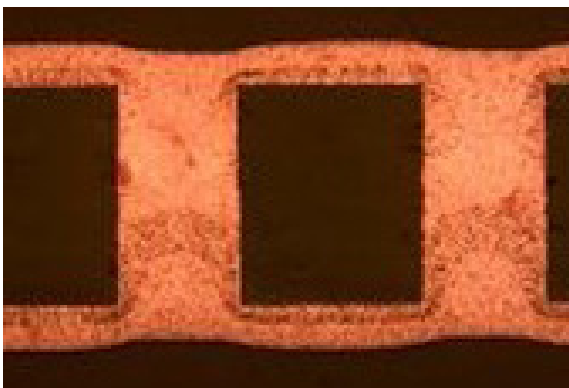


Systek THF

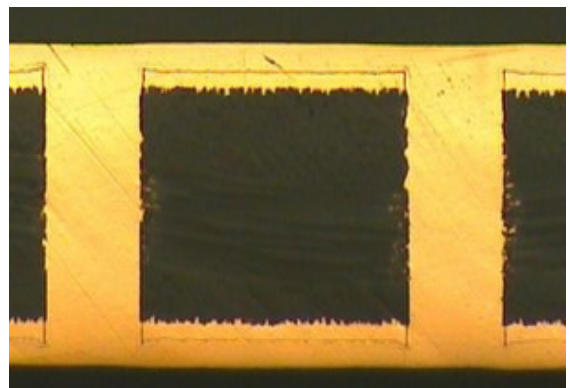


Solid Copper Filled Through Holes in Fewer Steps

Competitive 2-Step Through Hole Filling



Systek THF



Systek THF Series: Less plating solutions to maintain and elimination of a metallic interface for increased reliability.